



Infrared Imaging and NDT

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Message from the Guest Editors

Dear Colleagues,

Infrared thermography (IRT) has become a mature and widely accepted technology with applications in many different fields—from medical to industrial. Passive thermography is used to measure temperature and to monitor machines, facilities, and products. Active IRT is mostly used in nondestructive testing (NDT) applications, where materials are subjected to external thermal stimulation.

Nondestructive testing using IRT is nowadays a fundamental technology used to verify the quality of materials and products. NDT is used to detect defects, but also to prevent future failures and ensure safe long-term operation. Infrared thermographic NDT has been proven to provide excellent results, enabling fast testing and presenting a far more cost-efficient solution than other technologies.

The Special Issue “Infrared Imaging and NDT” will focus on the recent advances and new developments in any area related to passive and active thermography, inviting the submission of both review and original research articles.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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